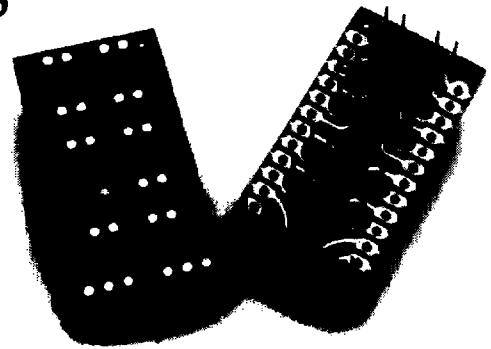


600-HG-HT HOLTITE® Socket Series LSI Adaptor Plug

MACHINED PIN ADAPTORS

The 600-HG-HT family of LSI adaptors is similar to the 600-HG family, however, the I.C. need not be soldered because Holtite® Zero Profile socket contacts in the adaptor allow for the convenience and economy of pluggability.



624-HG16-HT

- Adaptor plugs are designed to interpose LSI packages to Augat patterned and universal style boards
- Designed for 20 thru 64 lead LSI devices on .300", .400", and .600" spacing
- Adaptor pins are located to prevent improper positioning within the patterned area
- LSI package is socketed into Holtite® Zero Profile socket contacts, thus promoting interchangeability of different IC's without the need to solder IC to adaptor

PART NUMBER DESIGNATIONS

PART NUMBER	FIG.	ACCEPTS COMPONENTS	PIN CONFIGURATION					SOLDERLESS WRAP PANEL INTERFACE	
			STYLE REF DIM.	INTERFACE PIN STYLES	LENGTH REF.	MATERIAL	PLATING THICKNESS	APPLICATION	FORMAT
616-HG2-HT	1	16 Pin square devices 1.91 Spaced .075	Round .018"	4	.145	Brass	20 Micro inches Gold	16 Pin square pkg. to IC patterns on .300 x .200 x .300 row centers	VERT
620-HG16-HT	2	Up to 20 Leads 7.62 x 2.54 .300 x .100		2	.155	Phosphor Bronze		Adapts LSI to 14 and 16 pin IC patterns on .300 x .200 x .300 row centers	HORIZ
622-HG18-HT	3	Up to 22 Leads 10.16 x 2.54 .400 x .100	Square .025"	N/A	.470	Brass	10 Micro inches Gold	Adapts LSI to 14 and 16 pin IC patterns on .300 x .200 x .300 row centers	VERT
624-HG29-HT	4A	24 Pin DIPS 7.62 x 2.54 .300 x .100	Round .018"	4	.145	Brass	20 Micro inches Gold on dummy pins	Adapts 24 pin DIP's on .300 row centers up to .400 row centers	VERT (24 Pin DIP Adaptors)
624-HG26-HT	4B	24 Pin Dips 10.16 x 2.54 .400 x .100						Adapts 24 pin DIP's on .300 row centers up to .600 row centers	
624-HG28-HT	4C	24 Pin DIPS 10.16 x 2.54 .400 x .100						Adapts 24 pin DIP's on .400 row centers down to .300 row centers	
624-HG24-HT	4D	24 Pin DIPS 10.16 x 2.54 .400 x .100						Adapts 24 pin DIP's on .400 row centers up to .600 row centers	

*Consult factory for 28 position adaptors. Manufactured under one or more of U.S. patents 4,097,101 and 4,097,810 and patents in foreign countries

600-HG-HT Series

PART NUMBER DESIGNATIONS

PART NUMBER	FIG.	ACCEPTS COMPONENT	PIN CONFIGURATION				PLATING THICKNESS	SOLDERLESS WRAP PANEL INTERFACE	
			STYLE REF. DIM.	INTERFACE PIN STYLES	LENGTH REF	MATERIAL		APPLICATION	FORMAT
624-HG25-HT	4E	24 pin DIP's 15.24×2.54 .600 x .100	Round .018	4		Brass	20 Micro inches on dummy pins	Adapts 24 pin DIP's On .600 row centers down to .300 row centers	VERT (24 Pin DIP Adaptors)
624-HG22-HT	4F							10 Micro inches Gold on socket terminal pins	
624-HG116-HT	5	16 pin DIP's 7.62×2.54 .300 x .100					Special adaptor for 16 pin DIP's. See Fig. 5	VERT	
632-HG16-HT	6	Up to 32 Leads 22.86×2.54 .900 x .100		2	.155	Phosphor Bronze		Adapts LSI to 14 and 16 pin IC patterns on .300 x .200 x .300 row centers	HORIZ
632-HG17-HT	7	Up to 32 Leads 22.86×2.54 .900 x .100		4	.145	Brass		Adapts LSI to 14 and 16 pin IC patterns on .300 x .200 x .300 row centers	VERT
640-HG22-HT	8	Up to 40 Leads 15.25×2.54 .600 x .100		2	.155	Phosphor Bronze	20 Micro inches Gold	Adapts LSI to ECL panels on .300 x .100 x .300 row centers	VERT
648-HG16-HT	9	Up to 48 Leads 15.25×2.54 .600 x .100		2				Adapts LSI to 14 and 16 pin IC patterns on .300 x .200 x .300 row patterns	HORIZ
648-HG1-HT	10	Up to 48 Leads quad-in-line devices 15.25×2.54 20.32×2.54 .600 x .100 .800 x .100		2				Adapts quad-in-line devices to 14 and 16 pin IC patterns on .300 x .300 x .300 row centers	VERT
648-HG3-HT	11			2				Adapts quad-in-line devices to universal IC patterns on .300 x .300 x .300 on row centers	HORIZ
664-HG16-HT	12	Up to 64 Leads 22.86×2.54 .900 x .100		2					Adapts LSI to 14 and 16 pin IC patterns on .300 x .200 x .300 row centers

TYPICAL PERFORMANCE CHARACTERISTICS

BULK RESISTANCE	8 milliohms max.
CAPACITANCE	4 pico Farads max.
CURRENT	3 Amp DC (pin rating)
OPERATING VOLTAGE	500 Volts, not to exceed limit of interconnected device
DIELECTRIC WITHSTANDING VOLTAGE (DWV)	1000 Volts at sea level, 300 Volts at 50,000 feet
INSULATION RESISTANCE	2×10^7 Ohms
OPERATING TEMPERATURE	-50° C to -125° C
SOLDERABILITY	Per MIL-STD-202, Method 208

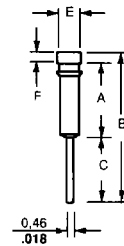
600-HG-HT Series

MATERIAL SPECIFICATIONS

BOARD062" Thick FR4 glass epoxy, 2 ounces copper circuitry FLGFN062/0 AIIIB per MIL-P-13949, rated 94-V or better
PLATING	200 Micro-inch electro tin
PINS	Phosphor bronze per QQ-P-330, Comp. A or brass per QQ-B-226
PLATING	Gold, refer to part number designation for thickness or tin, refer to part number designation for thickness
CONTACT	Beryllium copper, 30 μ " gold plated

INTERFACE PIN STYLES

PIN REFERENCE NUMBER	PART	A $\pm .010$	B $\pm .005$	C $\pm .005$	D $\pm .001$	E $\pm .001$	F $\pm .001$
1	8128-44P2	4.83 .190	9.55 .376	3.94 .155	1.41 .056	1.57 .062	0.76 .030
2	8149-3P4	3.18 .125	7.62 .300	3.94 .155	1.02 .040	1.27 .050	0.51 .020
3	8149-3P2	1.57 .062	6.05 .238	3.94 .155	1.02 .040	1.27 .050	0.51 .020
4	8128-94P3/P4	3.43 .135	7.62 .300	3.68 .145	0.99 .039	1.27 .050	5.08 .020



INTERFACE PIN

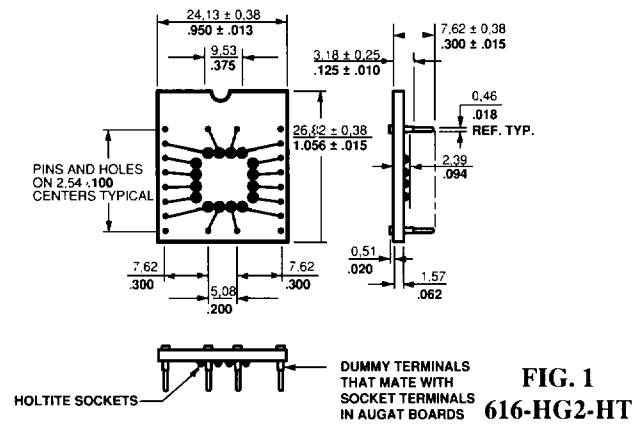


FIG. 1
616-HG2-HT

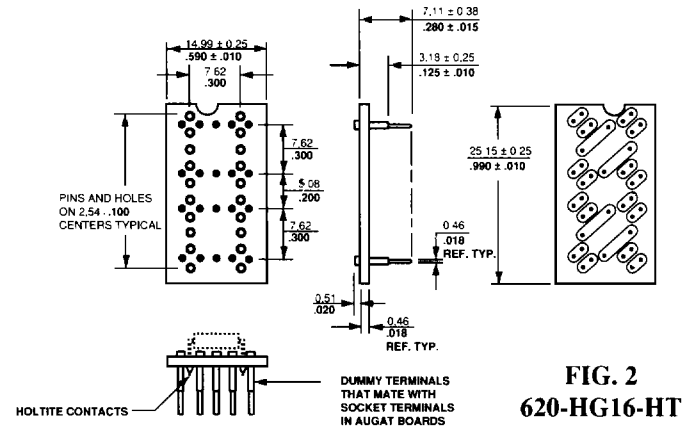


FIG. 2
620-HG16-HT

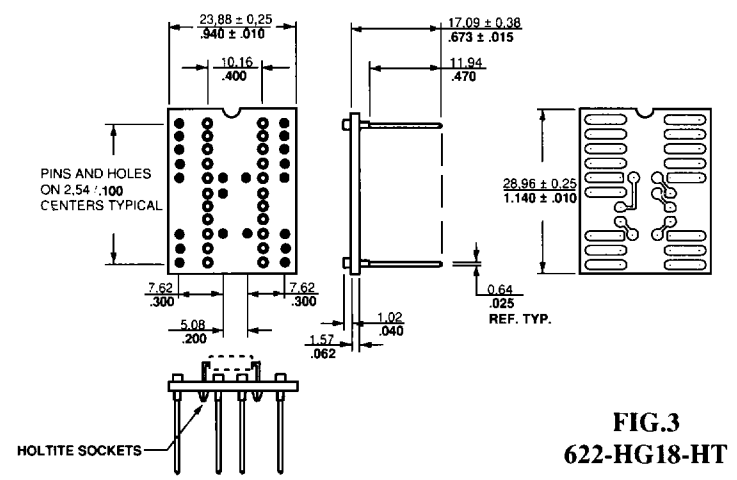
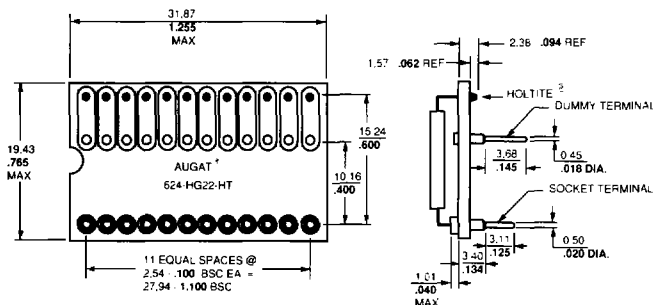
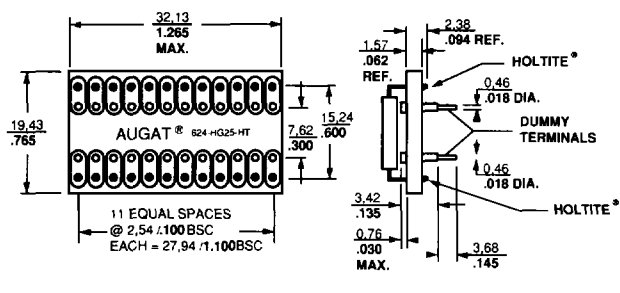
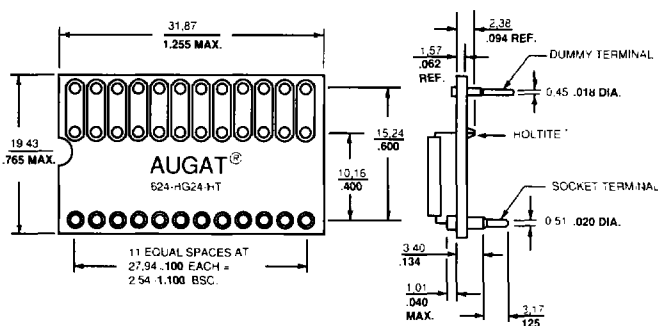
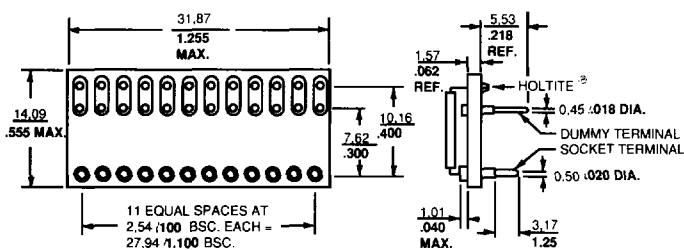
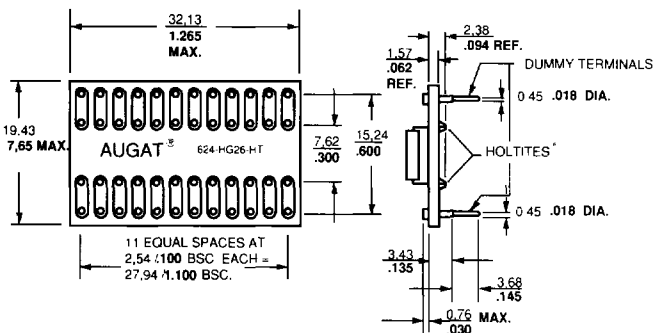
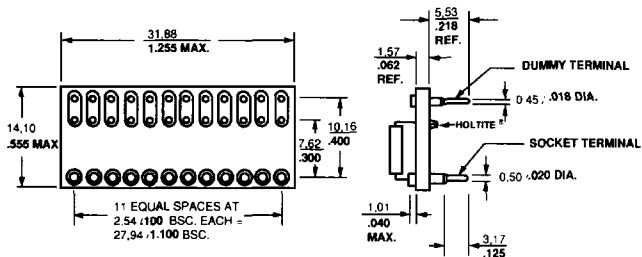


FIG. 3
622-HG18-HT

600-HG-HT Series



600-HG-HT Series

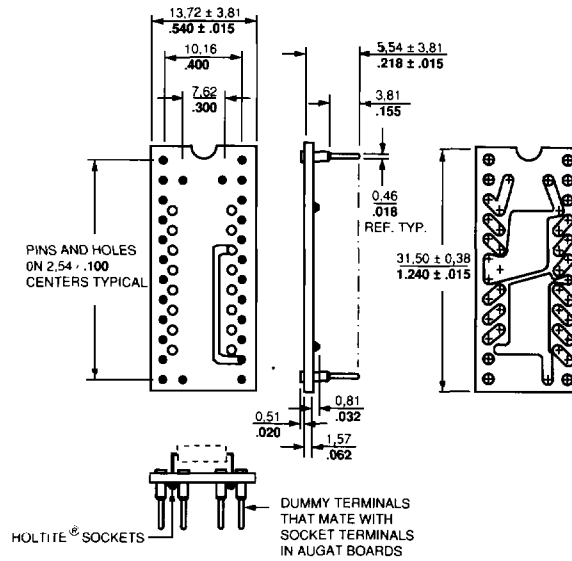


FIG. 5
624-HG116-HT

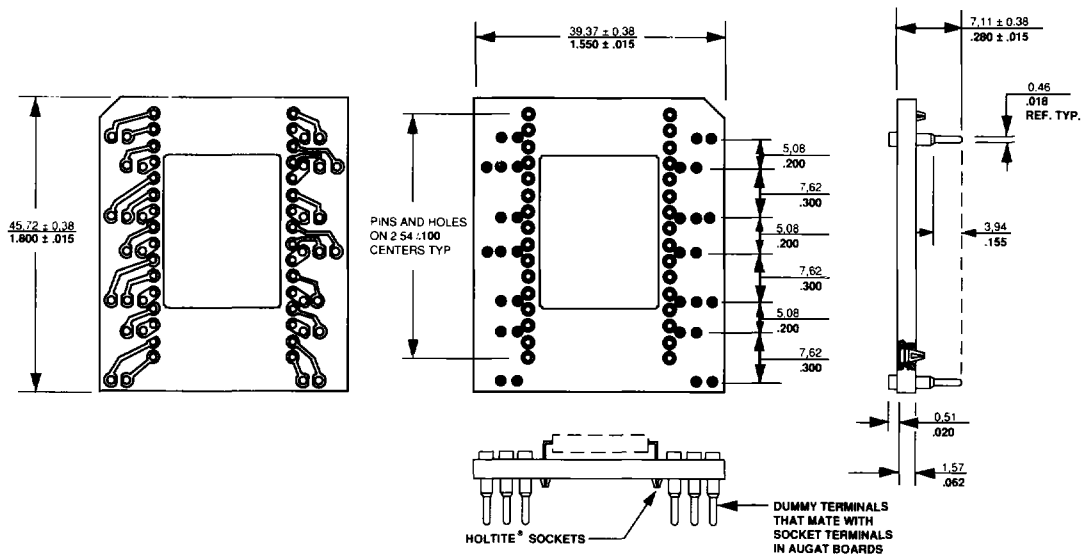


FIG. 6
632-HG16-HT

600-HG-HT Series

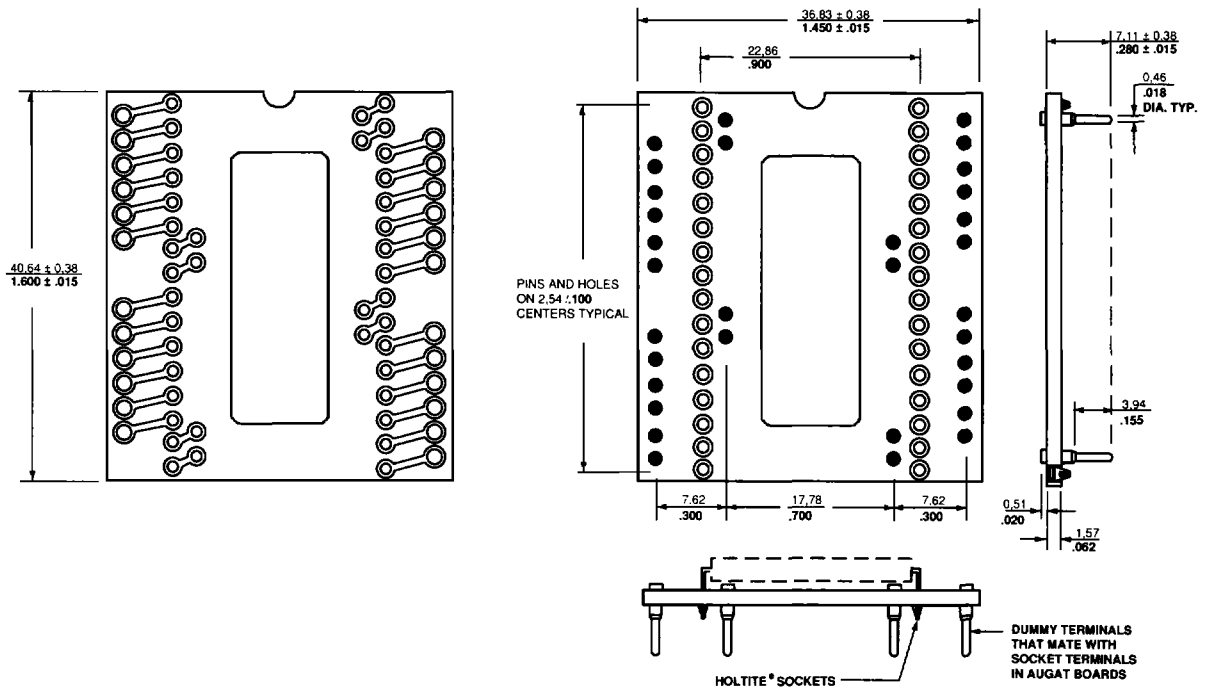


FIG. 7
632-HG17-HT

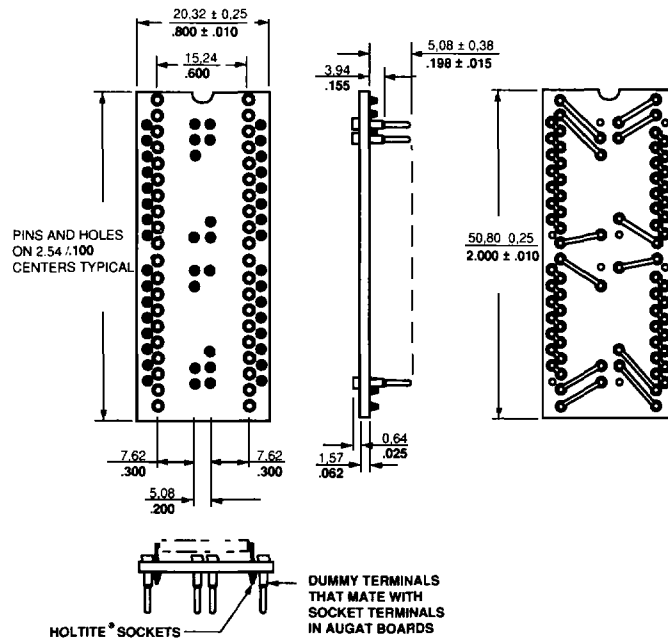
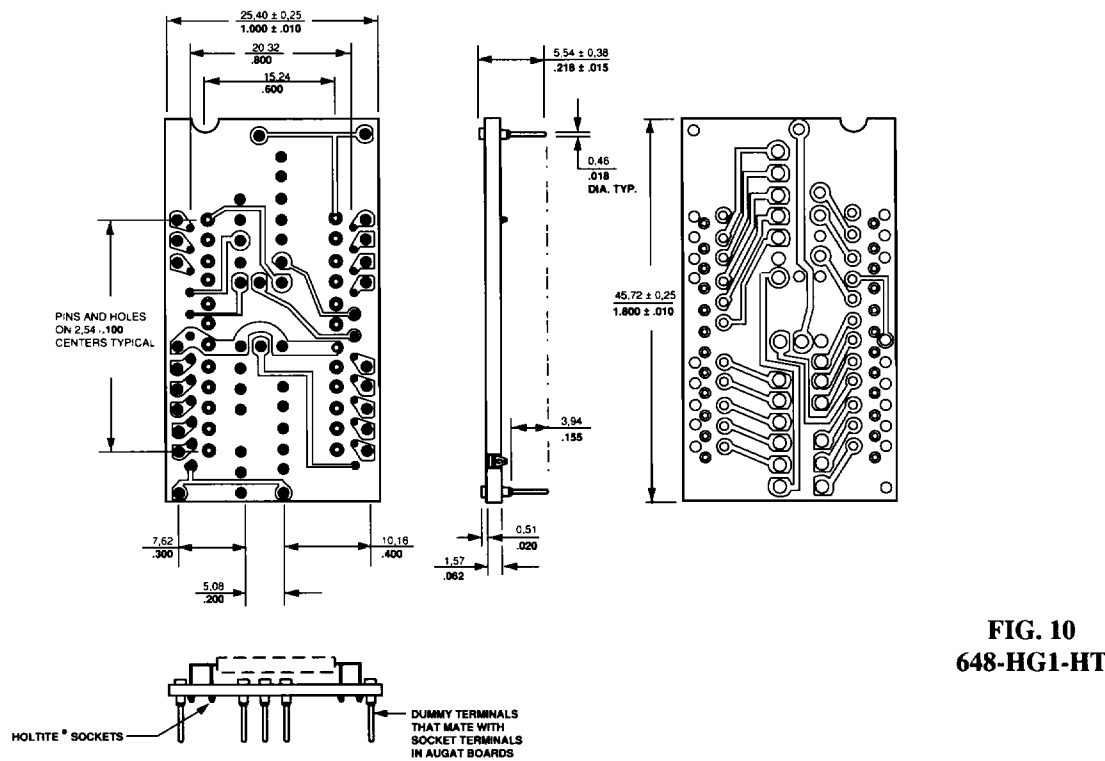
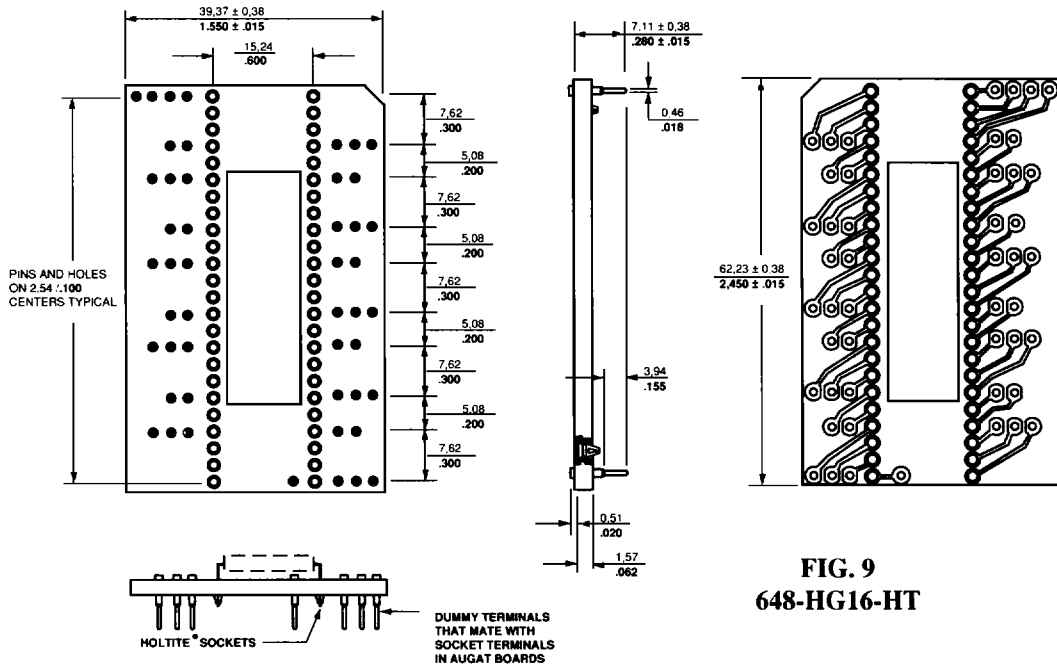


FIG. 8
640-HG22-HT

600-HG-HT Series



600-HG-HT Series

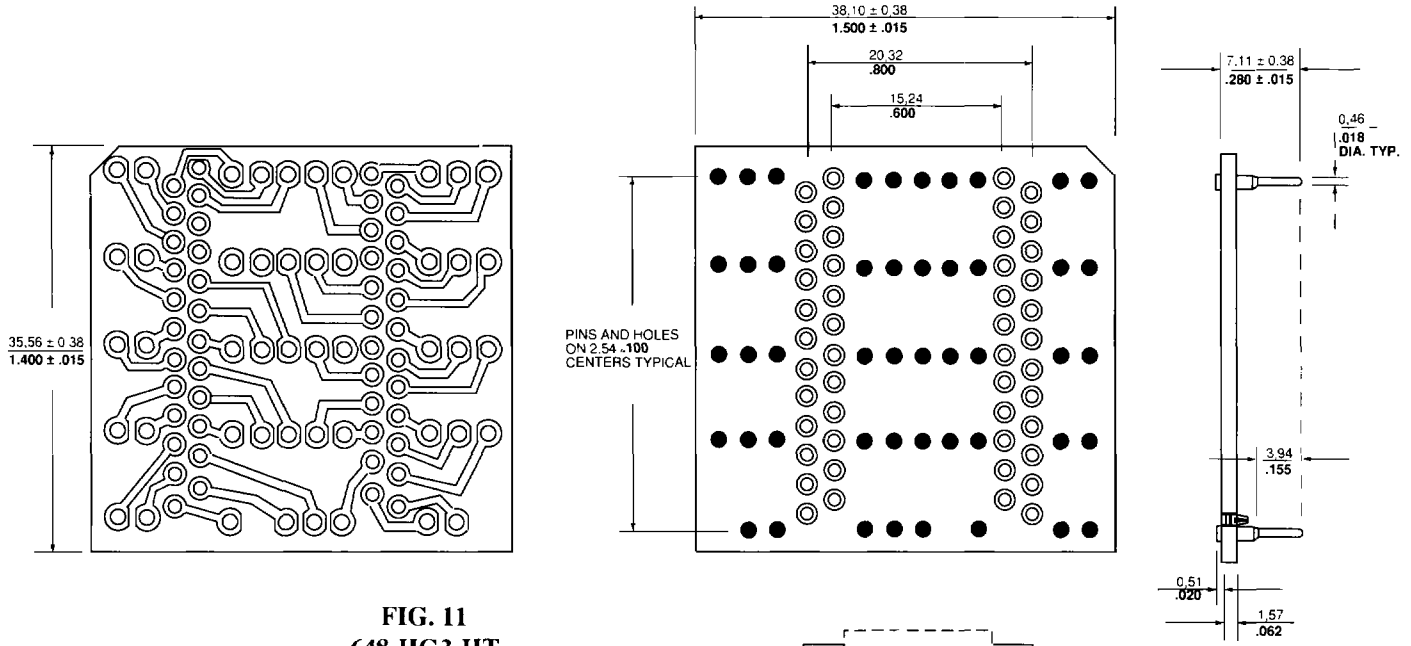


FIG. 11
648-HG3-HT

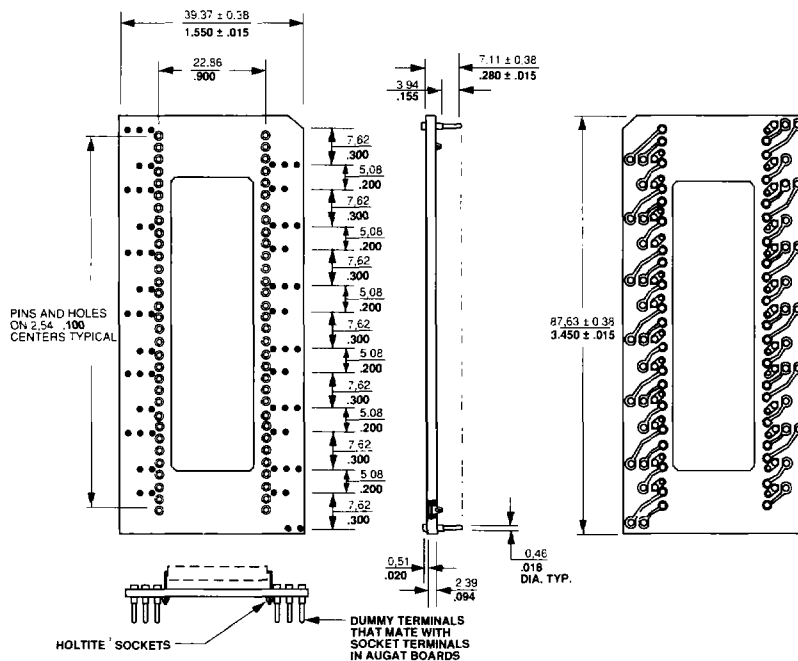
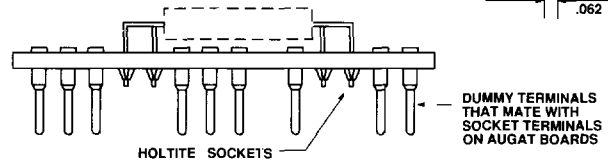


FIG. 12
664-HG16-HT